

NOT RECOMMENDED FOR NEW DESIGN USE HBS410



TT410

4A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Product Summary (@TA = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	I _R (μA)
1000	4	1.0	5

Features and Benefits

- Glass Passivated Die Construction
- Compact, Thin Profile Package Design
- Low Forward Voltage Drop Improves Power Efficiency
- · High Current and Surge Capability
- Reliable Robust Construction
- Ideal for SMT Manufacturing
- Rated at 1000V PRV
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

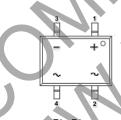
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

Mechanical Data

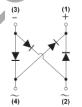
- Case: TT
- Case Material: Molded Plastic.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: As Marked on Body
- Weight: 0.297 grams (Approximate)



Top View



Pin Diagram



Internal Schematic

Ordering Information (Note 4)

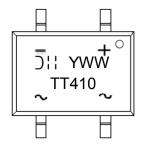
Part Number	Compliance	Case	Packaging
TT410-13	Commercial	TT	1,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
- <1000ppm antimony compounds.

 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



TT410= Product Type Marking Code

Oli = Manufacturers' Code Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 7 = 2017)

WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	1,000	>
RMS Reverse Voltage	V _{R(RMS)}	700	V
Average Rectified Output Current (Note 5) @ T _A = +25°C	Io	4.0	Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	120	Α
Non-Repetitive Peak Forward Surge Current, 1.0ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	240	Α
I ² t Rating for Fusing (1ms < t < 8.3ms)		59	A ² S

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	R ₀ JA	13	°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	R _{0JL}	8	°C/W
Typical Thermal Resistance, Junction to Case (Per Element)	Rejc	3	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	1,000	1	1	V	I _R = 10μA
Forward Voltage (Per Element)	VE		0.91	1.0	V	I _F = 2A, T _A = +25°C
Forward Voltage (Fer Element)	VF	_	0.80	1	V	I _F =2A, T _A = +125°C
Leakage Current (Note 6) (Per Element)		-	0.15	5		V _R = 1,000V, T _A = +25°C
Leakage Current (Note of (Per Liement)	IR	_	55	500	μΑ	V _R = 1,000V, T _A = +125°C
Total Capacitance (Per Element)	Ст	_	40	_	pF	V _R = 4V, f = 1.0MHz

5. Device mounted on 15mmx12mmx1.6mm AL Pad attached on 100mmx75mmx27mm Fin heatsink. Thermal resistance test performed in accordance with JESD-51.
6. Short duration pulse test used to minimize self-heating effect.



FIG.1- FORWARD CURRENT DERATING CURVE

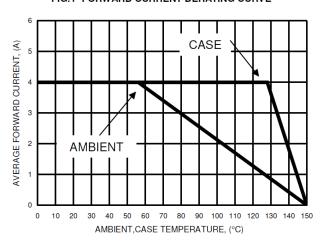


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

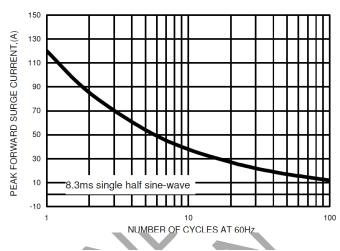


FIG.3- TYPICAL FORWARD CHARACTERISTICS

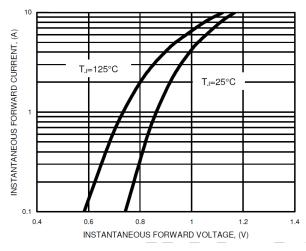


FIG.4- TYPICAL JUNCTION CAPACITANCE

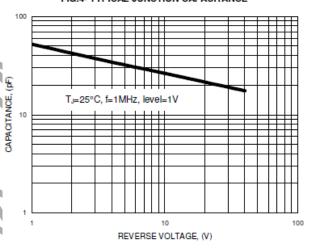
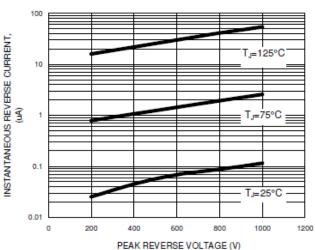


FIG.5- TYPICAL REVERSE CHARACTERISTICS

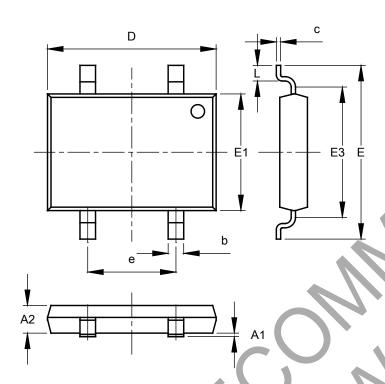




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

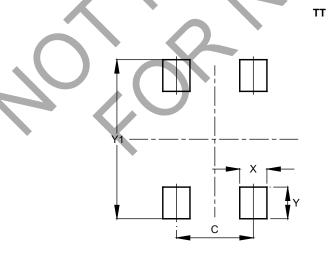
TT



TI					
Dim	Min	Max	TYP		
A1	0.10	0.20			
A2	1.40	1.60	1		
þ	0.70	0.90			
С	0.15	0.35	1		
D	9.45	9.75	1		
E	9.75	10.05	-		
E1	6.30	6.75			
E3	7.85	8.15			
е	4.90	5.10			
L	0.45	0.95			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)		
С	5.00		
Х	1.80		
Υ	2.10		
Y1	11.70		



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